PRODUCT BULLETIN
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21 May 2008

SUBJECT: ON Semiconductor Product Bulletin #PB16120

TITLE: Discontinuance of Dry Pack for SC88A /SC70-5 at On Seremban site

PROPOSED FIRST SHIP DATE: 21 May 2008

AFFECTED PRODUCT DIVISION: Automotive & Power Regulation Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor sales office or <Beatriz.Lofts@onsemi.com>

NOTIFICATION TYPE:
ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact your local ON Semiconductor sales office.

DESCRIPTION AND PURPOSE:
The SC88A / SC70-5 have recently been qualified at the On Semiconductor Seremban assembly site. The Final PCN#16092 can be found at www.onsemi.com. The SC88A /SC70-5 packages assembled at the Seremban factory meet the requirements of Moisture Sensitivity Level 1 (MSL 1) @ 260C level. These devices were previously qualified to MSL3 in ATP (Amkor Technology) which required the use of Dry Packaging Techniques. Effective June 2, 2008, dry packing will be discontinued for the following devices. Box labelling will be changed to reflect the MSL1 @260 C rating.

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AFFECTED DEVICE LIST

PART
NCP502SQ15T1G
NCP502SQ18T1G
NCP502SQ25T1G
NCP502SQ27T1G
NCP502SQ28T1G
NCP502SQ29T1G
NCP502SQ30T1G
NCP502SQ31T1G
NCP502SQ33T1G
NCP502SQ34T1G
NCP502SQ35T1G
NCP502SQ36T1G
NCP502SQ37T1G
NCP502SQ50T1G
NCP512SQ13T1G
NCP512SQ15T1G
NCP512SQ18T1G
NCP512SQ22T1G
NCP512SQ25T1G
NCP512SQ27T1G
NCP512SQ28T1G
NCP512SQ30T1G
NCP512SQ31T1G
NCP512SQ33T1G
NCP512SQ50T1G
NCP612SQ15T1G
NCP612SQ18T1G
NCP612SQ25T1G
NCP612SQ27T1G
NCP612SQ28T1G
NCP612SQ30T1G
NCP612SQ31T1G
NCP612SQ33T1G
NCP612SQ37T1G
NCP612SQ50T1G
NCV612SQ15T1G
NCV612SQ18T1G
NCV612SQ25T1G
NCV612SQ27T1G
NCV612SQ28T1G
NCV612SQ30T1G
NCV612SQ31T1G
NCV612SQ33T1G
NCV612SQ50T1G
NCS2001SQ1T2G
NCS2001SQ2T2G